SCOPE OF CLAIMED INVENTION:

1. A semiconductor device characterized in comprising:

a first semiconductor chip mounted on a substrate;

a second semiconductor chip mounted on the first semiconductor chip, the second semiconductor chip being larger than the first semiconductor chip;

a base member that is disposed between the second semiconductor chip and the substrate; and

a connection member disposed below the substrate,

wherein the second semiconductor chip is supported by the base member.

2. A semiconductor device characterized in comprising:

a first semiconductor chip mounted on a substrate;

a second semiconductor chip mounted on the first semiconductor chip, the second semiconductor chip being larger than the first semiconductor chip;

a filler layer that is provided between the second semiconductor chip and the substrate; and

a connection member disposed below the substrate,

wherein the second semiconductor chip is supported by the filler layer.

3. A method for manufacturing a semiconductor device, the method characterized in comprising the steps of:

mounting a first semiconductor chip on a substrate;

mounting a base member outside the first semiconductor chip on the substrate; and

mounting a second semiconductor chip that is larger than the first semiconductor chip on the first semiconductor chip, in a manner that the second semiconductor chip is supported by the base member.

4. A method for manufacturing a semiconductor device, the method characterized in comprising the steps of:

mounting a first semiconductor chip on a substrate,

mounting a second semiconductor chip that is larger than the first semiconductor chip on the first semiconductor chip; and

providing a filler layer in a manner to support the second semiconductor chip.